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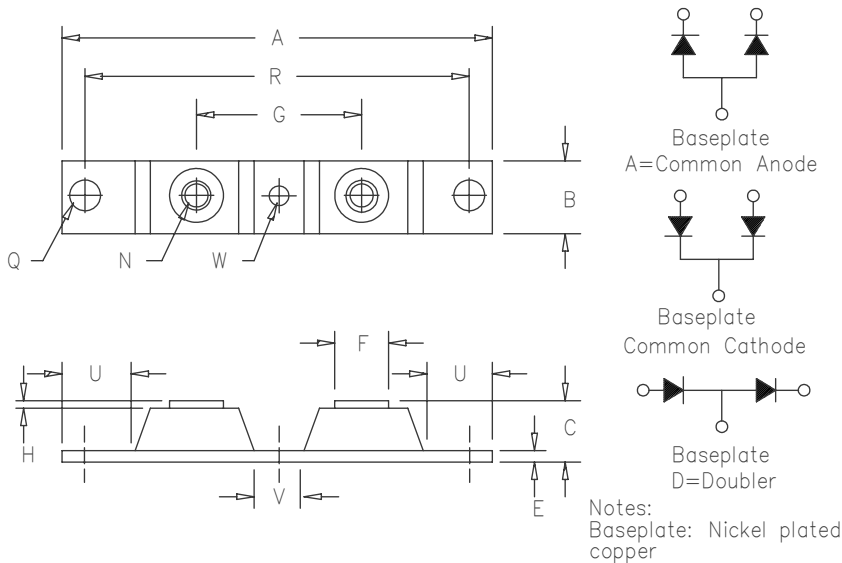
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# Schottky PowerMod

## CPT40080–CPT400100



Dim.	Inches		Millimeters		Notes
	Min.	Max.	Min.	Max.	
A	---	3.630	---	92.20	
B	0.700	0.800	17.78	20.32	
C	---	0.630	---	16.00	
E	0.120	0.130	3.05	3.30	
F	0.490	0.510	12.45	12.95	
G	1.375 BSC		34.92 BSC		
H	0.010	---	0.25	---	
N	---	---	---	---	1/4-20
Q	0.275	0.290	6.99	7.37	Dia.
R	3.150 BSC		80.01 BSC		
U	0.600	---	15.24	---	
V	0.312	0.340	7.92	8.64	
W	0.180	0.195	4.57	4.95	Dia.

Microsemi Catalog Number	Industry Part Number	Working Peak Reverse Voltage	Repetitive Peak Reverse Voltage
CPT40080*	403CNQ080 MBR40080CT	80V	80V
CPT40090*		90V	90V
CPT400100*	403CNQ100 MBRP400100CTL MBR400100CT	100V	100V

\*Add Suffix A for Common Anode, D for Doubler

- Schottky Barrier Rectifier
- Guard Ring Protection
- 400 Amperes/80–100 Volts
- 175°C Junction Temperature
- Reverse Energy Tested
- ROHS Compliant

### Electrical Characteristics

Average forward current per pkg	I <sub>F(AV)</sub> 400 Amps	T <sub>C</sub> = 121°C, Square wave, R <sub>θJC</sub> = 0.16°C/W
Average forward current per leg	I <sub>F(AV)</sub> 200 Amps	T <sub>C</sub> = 121°C, Square wave, R <sub>θJC</sub> = 0.32°C/W
Maximum surge current per leg	I <sub>FSM</sub> 3000 Amps	8.3ms, half sine, T <sub>J</sub> = 175°C
Maximum repetitive reverse current per leg	I <sub>R(OV)</sub> 2 Amps	f = 1 KHZ, 25°C, 1μsec square wave
Max peak forward voltage per leg	V <sub>FM</sub> .89 Volts	I <sub>FM</sub> = 200A: T <sub>J</sub> = 25°C*
Max peak forward voltage per leg	V <sub>FM</sub> .69 Volts	I <sub>FM</sub> = 200A: T <sub>J</sub> = 175°C*
Max peak reverse current per leg	I <sub>RM</sub> 50 mA	V <sub>RRM, T<sub>J</sub></sub> = 125°C*
Max peak reverse current per leg	I <sub>RM</sub> 5.0 mA	V <sub>RRM, T<sub>J</sub></sub> = 25°C
Typical junction capacitance per leg	C <sub>J</sub> 4400 pF	V <sub>R</sub> = 5.0V, T <sub>C</sub> = 25°C

\*Pulse test: Pulse width 300μsec, Duty cycle 2%

### Thermal and Mechanical Characteristics

Storage temp range	T <sub>STG</sub>	-55°C to 175°C
Operating junction temp range	T <sub>J</sub>	-55°C to 175°C
Max thermal resistance per leg	R <sub>θJC</sub>	0.32°C/W Junction to case
Max thermal resistance per pkg	R <sub>θJC</sub>	0.16°C/W Junction to case
Typical thermal resistance (greased)	R <sub>θCS</sub>	0.08°C/W Case to sink
Terminal Torque		35–40 inch pounds
Mounting Base Torque (outside holes)		30–40 inch pounds
Mounting Base Torque (center hole)		8–10 inch pounds
center hole must be torqued first		
Weight		2.8 ounces (77 grams) typical

# CPT40080-CPT400100

Figure 1  
Typical Forward Characteristics - Per Leg

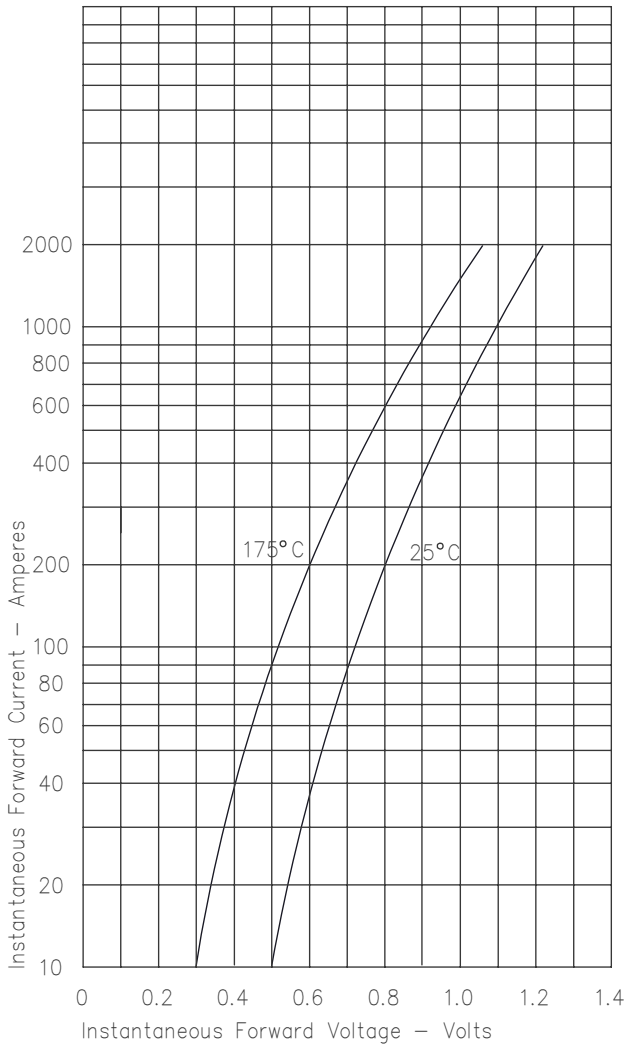


Figure 3  
Typical Junction Capacitance - Per Leg

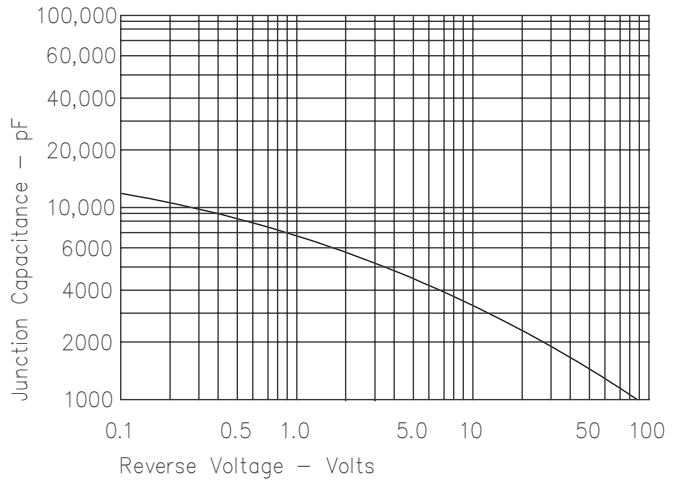


Figure 4  
Forward Current Derating - Per Leg

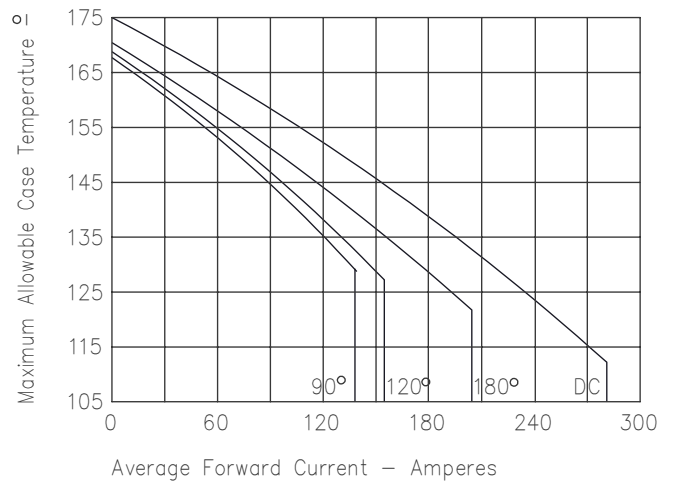


Figure 2  
Typical Reverse Characteristics - Per Leg

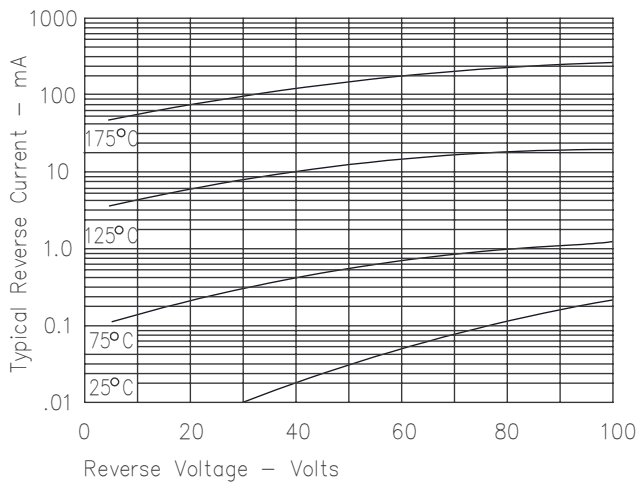
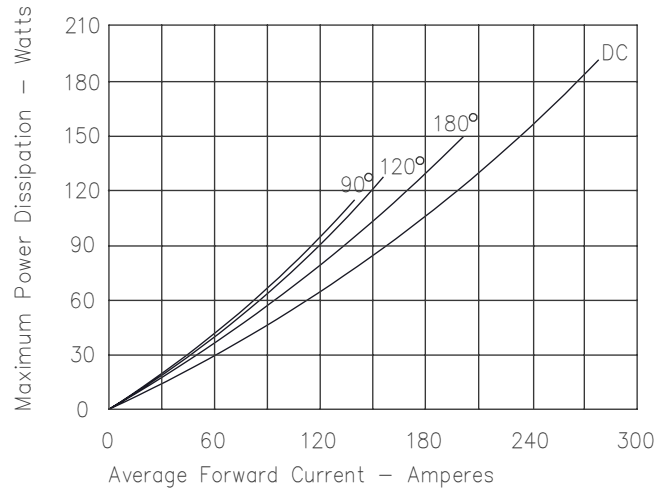


Figure 5  
Maximum Forward Power Dissipation - Per Leg



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